

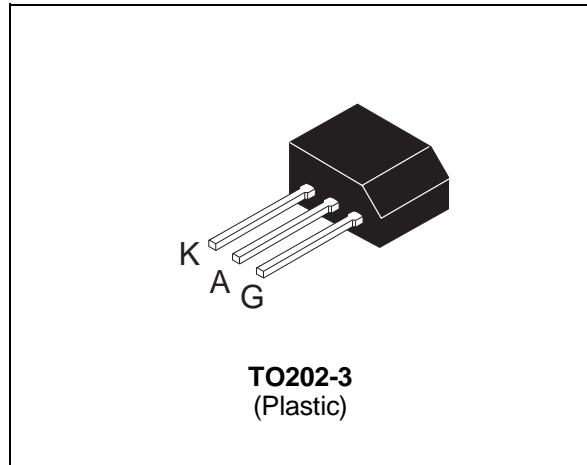
SENSITIVE GATE SCR

FEATURES

- $I_T(\text{RMS}) = 4\text{A}$
- $V_{DRM} = 400\text{V to } 800\text{V}$
- Low $I_{GT} < 200\mu\text{A}$

DESCRIPTION

The X04xxxF series of SCRs uses a high performance TOP GLASS PNPN technology. These parts are intended for general purpose applications where low gate sensitivity is required, like small engine ignition, SMPS crowbar protection, food processor.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$I_T(\text{RMS})$	RMS on-state current (180° conduction angle)	$T_c = 90^\circ\text{C}$	4	A
		$T_a = 25^\circ\text{C}$	1.35	
$I_T(\text{AV})$	Mean on-state current (180° conduction angle)	$T_c = 90^\circ\text{C}$	2.5	A
		$T_a = 25^\circ\text{C}$	0.9	
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = 25°C)	$t_p = 8.3\text{ ms}$	33	A
		$t_p = 10\text{ ms}$	30	
I^2t	I^2t Value for fusing	$t_p = 10\text{ ms}$	4.5	A^2s
dI/dt	Critical rate of rise of on-state current $I_G = 10\text{ mA}$ $dI_G/dt = 0.1\text{ A}/\mu\text{s}$		50	$\text{A}/\mu\text{s}$
T_{stg} T_j	Storage and operating junction temperature range		- 40, + 150 - 40, + 125	$^\circ\text{C}$
T_l	Maximum lead temperature for soldering during 10s at 4.5mm from case		260	$^\circ\text{C}$

Symbol	Parameter	Voltage			Unit
		D	M	N	
V_{DRM} V_{RRM}	Repetitive peak off-state voltage $T_j = 125^\circ\text{C}$ $R_{GK} = 1\text{K}\Omega$	400	600	800	V

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th(j-a)}	Junction to ambient	100	°C/W
R _{th(j-c)}	Junction to case for DC	7.5	°C/W

GATE CHARACTERISTICS

P_{G (AV)}= 0.2 W max. P_{GM} = 3 W max. (tp = 20 µs) I_{GM} = 1.2 A max. (tp = 20 µs)
V_{GD} = 0.1V min. (V_D=V_{DRM} R_L=3.3kΩ R_{GK} = 1 KΩ T_j= 125°C)

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions	Sensitivity			Unit	
		02	03	05		
I _{GT}	V _D =12V (DC) R _L =140Ω	T _j = 25°C	MIN	20	20	µA
			MAX	200	200	
V _{GT}	V _D =12V (DC) R _L =140Ω	T _j = 25°C	MAX	0.8	V	
V _{RGM}	I _{RG} =10µA	T _j = 25°C	MIN	8	V	
I _H	I _T = 50mA R _{GK} = 1 KΩ	T _j = 25°C	MAX	5	mA	
I _L	I _G =1mA R _{GK} = 1 KΩ	T _j = 25°C	MAX	6	mA	
V _{TM}	I _{TM} = 8A tp= 380µs	T _j = 25°C	MAX	1.8	V	
I _{DRM} I _{RRM}	V _D = V _{DRM} R _{GK} = 1 KΩ V _R = V _{RRM}	T _j = 25°C	MAX	5	µA	
		T _j = 110°C	MAX	200		
dV/dt	V _D =67%V _{DRM} R _{GK} = 1 KΩ	T _j = 110°C	MIN	10 15 15	V/µs	

ORDERING INFORMATION

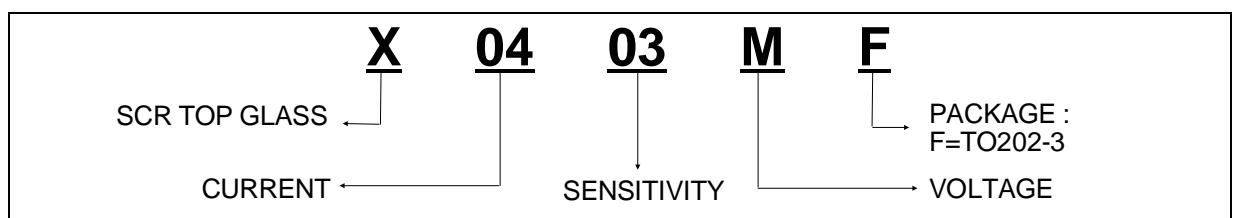


Fig.1 : Maximum average power dissipation versus average on-state current.

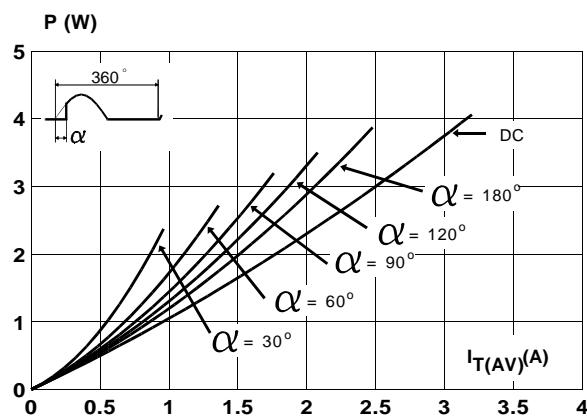


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperature (Tamb and Tcase).

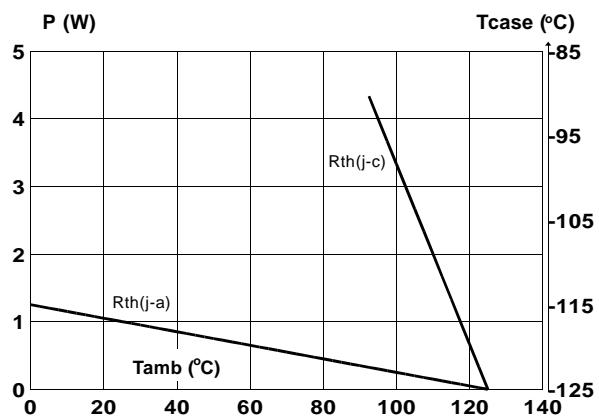


Fig.3 : Average on-state current versus case temperature.

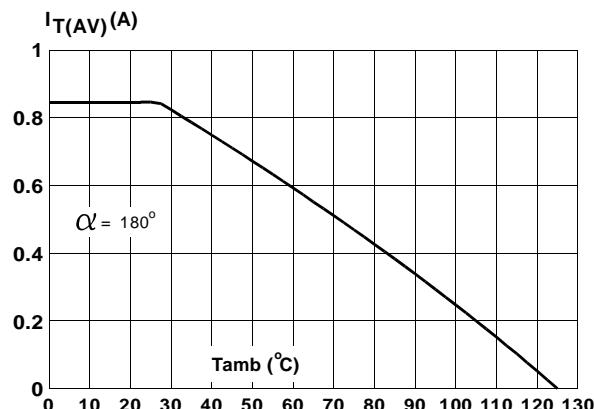


Fig.4 : Relative variation of thermal impedance junction to ambient versus pulse duration.

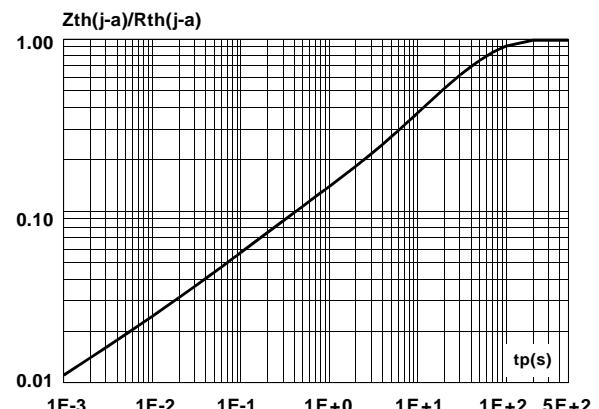


Fig.5 : Relative variation of gate trigger current and holding current versus junction temperature.

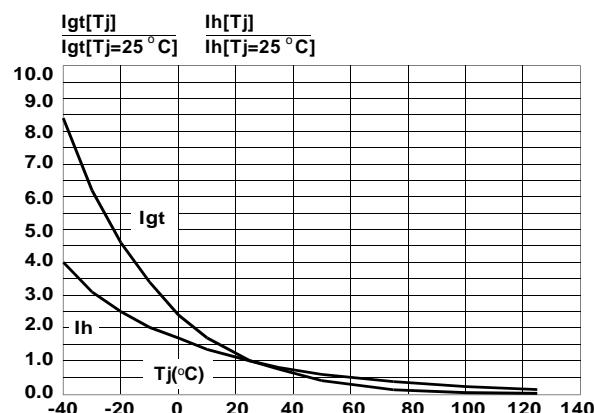
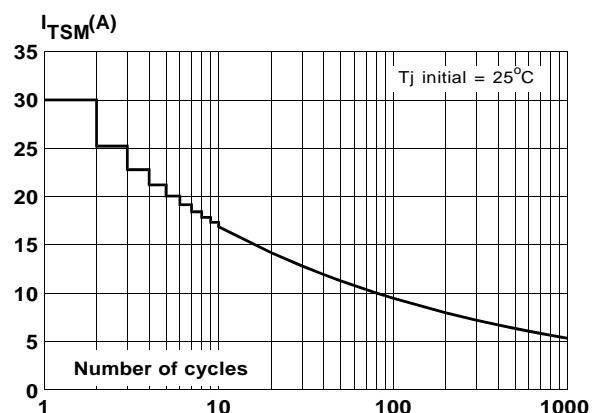


Fig.6 : Non repetitive surge peak on-state current versus number of cycles.



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Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t_p \leq 10\text{ms}$, and corresponding value of I^2t .

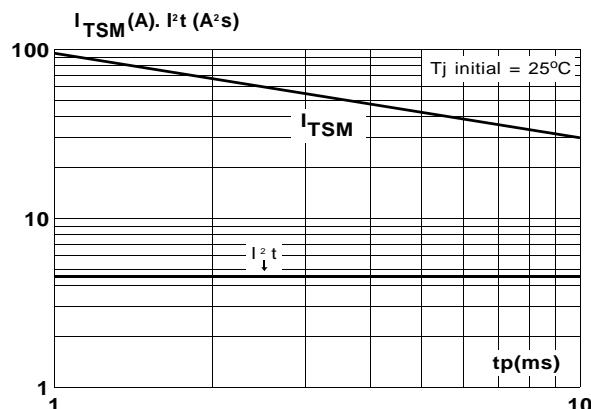
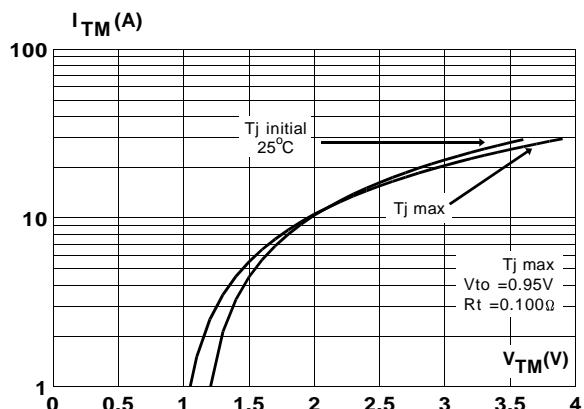


Fig.8 : On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA

TO202-3 (Plastic)

The mechanical drawing shows two views of the TO202-3 package. The left view shows top and side cross-sections with dimensions: A (width), C (height), D (lead thickness), F (lead height), H (lead pitch), J (lead length), M (lead width), N (lead thickness), O (lead height), P (lead thickness), and N1 (lead thickness). The right view shows a side profile with dimension C. A table to the right lists these dimensions in millimeters and inches.

REF.	DIMENSIONS			
	Millimeters		Inches	
	Typ.	Max.	Typ.	Max.
A		10.1		0.398
C	7.3		0.287	
D	10.5		0.413	
E	7.4		0.290	
F		1.5		0.059
H	0.51		0.020	
J	1.5		0.059	
M	4.5		0.177	
N		5.3		0.209
N1	2.54		0.100	
O		1.4		0.055
P		0.7		0.028

Marking : type number

Weight : 1 g

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